

MOS FIELD EFFECT TRANSISTOR

NP82N055CHE,NP82N055DHE,NP82N055EHE,NP82N055KHE

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

These products are N-channel MOS Field Effect Transistor designed for high current switching applications.

FEATURES

- Channel temperature 175 degree rated
- Super low on-state resistance

 $R_{DS(on)} = 8.6~m\Omega$ MAX. (Vgs = 10 V, Ip = 41 A)

- Low Ciss: Ciss = 3500 pF TYP.
- Built-in gate protection diode

ORDERING INFORMATION

PART NUMBER	PACKAGE
NP82N055CHE	TO-220AB
NP82N055DHE	TO-262
NP82N055EHE	TO-263 (MP-25ZJ)
NP82N055KHE	TO-263 (MP-25ZK)

(TO-220AB)



(TO-262)



(TO-263)



ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

	•	•	
Drain to Source Voltage (Vgs = 0 V)	VDSS	55	V
Gate to Source Voltage (Vps = 0 V)	Vgss	±20	V
Drain Current (DC) Note1	ID(DC)	±82	Α
Drain Current (pulse) Note2	ID(pulse)	±300	Α
Total Power Dissipation (T _A = 25°C)	Рт	1.8	W
Total Power Dissipation (Tc = 25°C)	Рт	163	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Single Avalanche Current Note3	las	72 / 49 / 17	Α
Single Avalanche Energy Note3	Eas	51 / 240 / 289	mJ

Notes 1. Calculated constant current according to MAX. allowable channel temperature.

- **2.** PW \leq 10 μ s, Duty cycle \leq 1%
- 3. Starting T_{ch} = 25°C, V_{DD} = 28 V, R_G = 25 Ω , V_{GS} = 20 \rightarrow 0 V (See Figure 4.)

THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	0.92	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W

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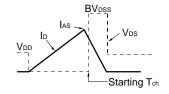


ELECTRICAL CHARACTERISTICS (TA = 25°C)

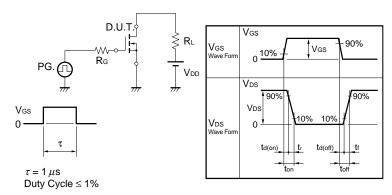
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Ipss	V _{DS} = 55 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	V _G S = ±20 V, V _D S = 0 V			±10	μΑ
Gate to Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2.0	3.0	4.0	V
Forward Transfer Admittance	yfs	V _{DS} = 10 V, I _D = 41 A	19	38		S
Drain to Source On-state Resistance	RDS(on)	Vgs = 10 V, ID = 41 A		6.9	8.6	mΩ
Input Capacitance	Ciss	V _{DS} = 25 V		3500	5250	pF
Output Capacitance	Coss	V _G S = 0 V		550	830	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		270	490	pF
Turn-on Delay Time	td(on)	V _{DD} = 28 V, I _D = 41 A		31	69	ns
Rise Time	tr	V _{GS(on)} = 10 V		18	45	ns
Turn-off Delay Time	td(off)	$R_G = 1 \Omega$		61	120	ns
Fall Time	tf			19	47	ns
Total Gate Charge	Q _G	V _{DD} = 44 V		65	100	nC
Gate to Source Charge	Qgs	Ves = 10 V ID = 82 A		18		nC
Gate to Drain Charge	Q _{GD}			24		nC
Body Diode Forward Voltage	VF(S-D)	I _F = 82 A, V _{GS} = 0 V		1.0		V
Reverse Recovery Time	trr	I _F = 82 A, V _{GS} = 0 V		45		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		63		nC

TEST CIRCUIT 1 AVALANCHE CAPABILITY

$\begin{array}{c} \text{D.U.T.} \\ \text{RG} = 25 \ \Omega \\ \text{Ves} = 20 \rightarrow 0 \ V \end{array}$



TEST CIRCUIT 2 SWITCHING TIME



TEST CIRCUIT 3 GATE CHARGE

TYPICAL CHARACTERISTICS (TA = 25°C)

Figure1. DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA

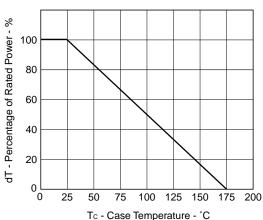


Figure.3 FORWARD BIAS SAFE OPERATING AREA

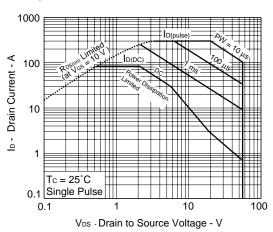


Figure2. TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

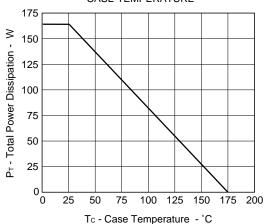


Figure4. SINGLE AVALANCHE ENERGY DERATING FACTOR

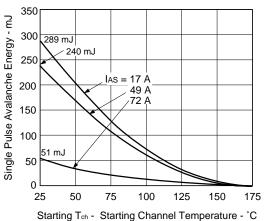
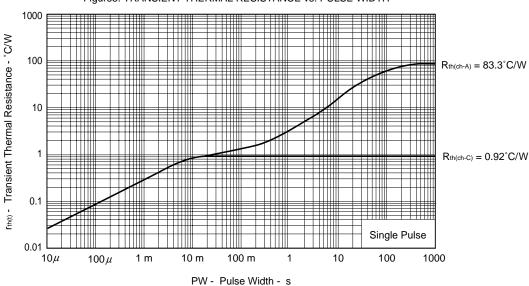


Figure 5. TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



Data Sheet D14138EJ5V0DS

Figure 6. FORWARD TRANSFER CHARACTERISTICS

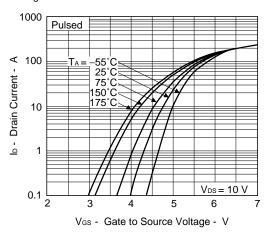


Figure8. FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

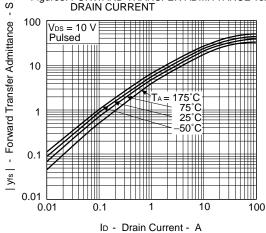


Figure 10. DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

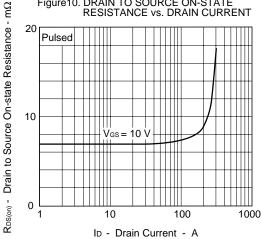
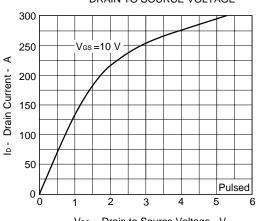


Figure 7. DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



V_{DS} - Drain to Source Voltage - V

Figure9. DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

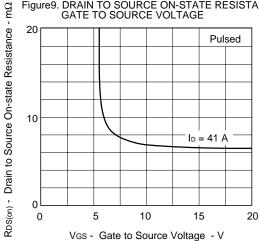
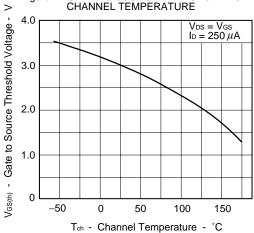
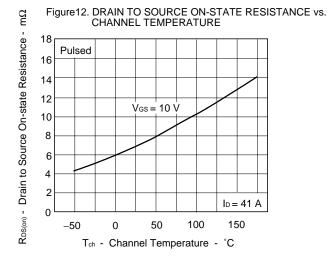
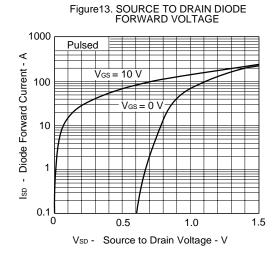


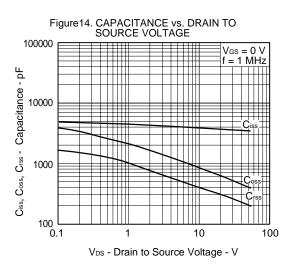
Figure 11. GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE

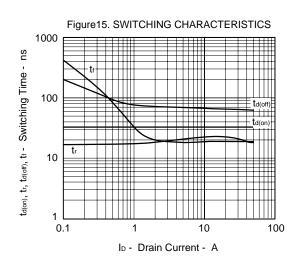


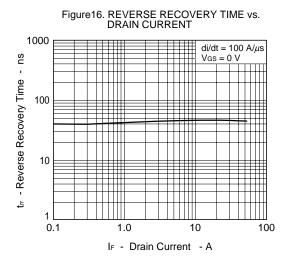
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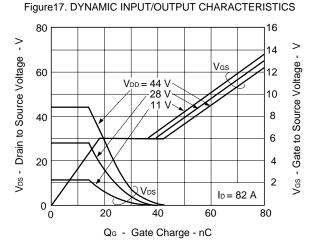








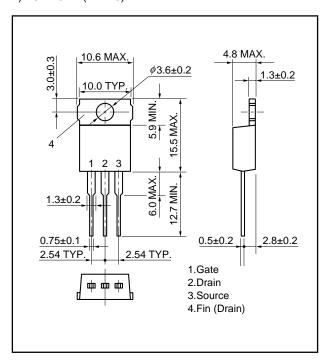




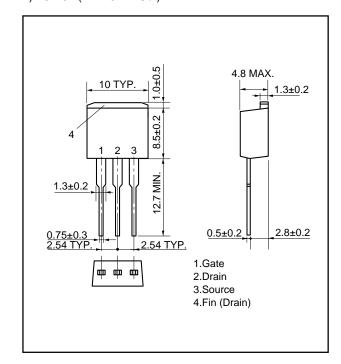
5

PACKAGE DRAWINGS (Unit: mm)

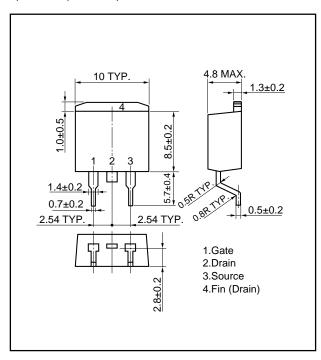
1) TO-220AB (MP-25)



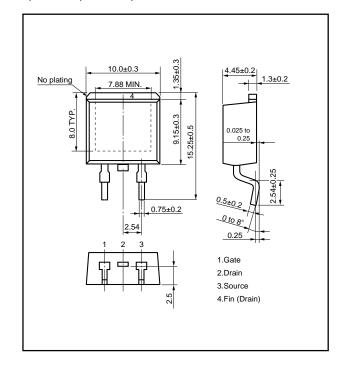
2) TO-262 (MP-25 Fin Cut)



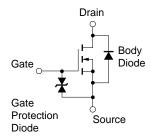
3) TO-263 (MP-25ZJ)



★ 4) TO-263 (MP-25ZK)



EQUIVALENT CIRCUIT



Remark

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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